- · Can Be Used as a 4-Bit Digital Comparator
- Input Clamping Diodes Simplify System Design
- Fully Compatible with Most TTL Circuits

FUNCTION TABLE

INP	UTS	ОUТРUТ
Α	В	Y
L	L	н
L	Н	L
н	L.	L
н	Н	н

H = high level, L = low level

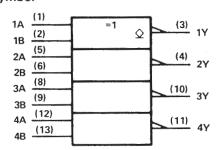
description

The 'LS266 is comprised of four independent 2-input exclusive-NOR gates with open-collector outputs. The open-collector outputs permit tying outputs together for multiple-bit comparisons.

logic symbol (each gate)



logic symbol†



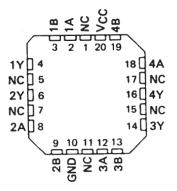
positive logic: $Y = \overline{A \oplus B} = AB + \overline{AB}$

Pin numbers shown are for D, J, N, and W packages.

SN54LS266 . . . J OR W PACKAGE SN74LS266 . . . D OR N PACKAGE (TOP VIEW)

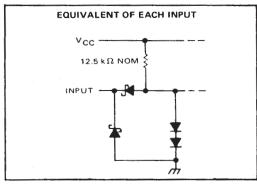
1A 1 14 VCC
1B 2 13 4B
1Y 3 12 4A
2Y 4 11 4Y
2A 5 10 3Y
2B 6 9 3B
GND 7 8 3A

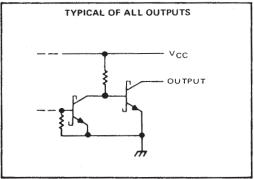
SN54LS266 ... FK PACKAGE (TOP VIEW)



NC - No internal connection

schematic of inputs and outputs







[†]This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

SN54LS266, SN74LS266 QUADRUPLE 2-INPUT EXCLUSIVE-NOR GATES WITH OPEN-COLLECTOR OUTPUTS

SDLS151 – DECEMBER 1972 – REVISED MARCH 1988

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)														7 '	V
Input voltage														7 '	V
Operating free-air temperature range:	SN54LS266		٠,								-5	5°C	c to	125°	С
	SN74LS266											0°	C t	o 70°	С
Storage temperature range															

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

	SI	SI	UNIT				
	MIN	NOM	MAX	MIN	NOM	MAX	CIVIT
Supply voltage, V _{CC}	4.5	5	5.5	4.75	5	5.25	٧
High-level output voltage, VOH			5.5			5.5	٧
Low-level output current, IOL			4			8	mA
Operating free-air temperature, T _A	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			SI	N54LS2	66	S	UNIT			
		TEST CON	MIN	TYP‡	MAX	MIN	TYP‡	MAX	ONT	
VIH	High-level input voltage			2			2			٧
VIL	Low-level input voltage					0.7			0.8	V
VIK	Input clamp voltage	VCC = MIN,	I _I = -18 mA			1.5			-1.5	٧
ЮН	High-level output current	V _{CC} = MIN, V _{IL} = V _{IL} max,	V _{IH} = 2 V, V _{OH} = 5.5 V			100			100	μА
VOL	Low-level output voltage	V _{CC} ≈ MIN, V _{IH} = 2 V,	IOL = 4 mA		0.25	0.4		0.25	0.4	V
VOL	Low-rever output vortage	VIL = VIL max	IOL = 8 mA					0.35	0.5	
- Lj	Input current at maximum input voltage	V _{CC} = MAX,	V1 = 7 V			0.2			0.2	mA
Чн	High-level input current	V _{CC} = MAX,	V ₁ = 2.7 V			40			40	μА
IL	Low-level input current	V _{CC} = MAX,	V ₁ = 0.4 V			-0.8			-0.8	mA
1cc	Supply current	V _{CC} = MAX,	See Note 2		8	13		8	13	mA

¹ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type. ‡ All typical values are at V_{CC} = 5 V, T_A = 25 C.

switching characteristics, VCC = 5 V, TA = 25°C

PARAMETER§	FROM (INPUT)	TEST CO	TEST CONDITIONS				UNIT
^t PLH	A or B	Other input low	CL = 15 pF,		18	30	ns
tPHL		Other Hipat low	$R_L = 2 k\Omega$,		18	30	1
tpLH	A or B	Other input high	See Note 3		18	30	ns
tPHL		Other input high	00011010		18	30	""

[§]tpLH = propagation delay time, low-to-high-level output



NOTE 2: 1_{CC} is measured with one input of each gate at 4.5 V, the other inputs grounded, and the outputs open

tpHL = propagation delay time, high-to-low-level output

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.





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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN54LS266J	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
SN74LS266D	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74LS266DR	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74LS266N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS266N3	OBSOLETE	PDIP	N	14		None	Call TI	Call TI
SN74LS266NSR	ACTIVE	SO	NS	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SNJ54LS266FK	OBSOLETE			20		None	Call TI	Call TI
SNJ54LS266J	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
SNJ54LS266W	ACTIVE	CFP	W	14	1	None	Call TI	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

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